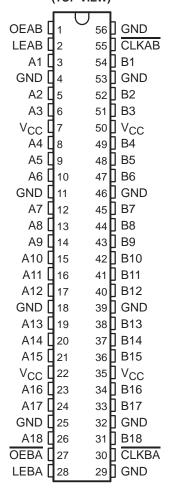
- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- UBT[™] (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent,
 Latched, or Clocked Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. OEAB is active-high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

SN54ABT16500B... WD PACKAGE SN74ABT16500B... DGG OR DL PACKAGE (TOP VIEW)



Data flow for B to A is similar to that of A to B but uses $\overline{\text{OEBA}}$, LEBA, and $\overline{\text{CLKBA}}$. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).



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SN54ABT16500B, SN74ABT16500B 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT16500B is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16500B is characterized for operation from -40° C to 85° C.

FUNCTION TABLET

	OUTPUT			
OEAB	LEAB	CLKAB	Α	В
L	Х	Х	Х	Z
Н	Н	X	L	L
Н	Н	Χ	Н	Н
Н	L	\downarrow	L	L
Н	L	\downarrow	Н	Н
Н	L	Н	Χ	в ₀ ‡ в ₀ §
Н	L	L	Χ	в ₀ §

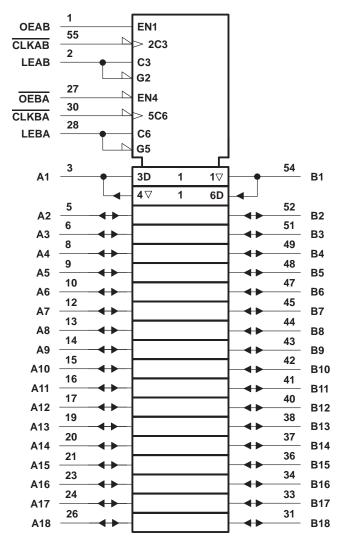
[†] A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.



[‡] Output level before the indicated steady-state input conditions were established

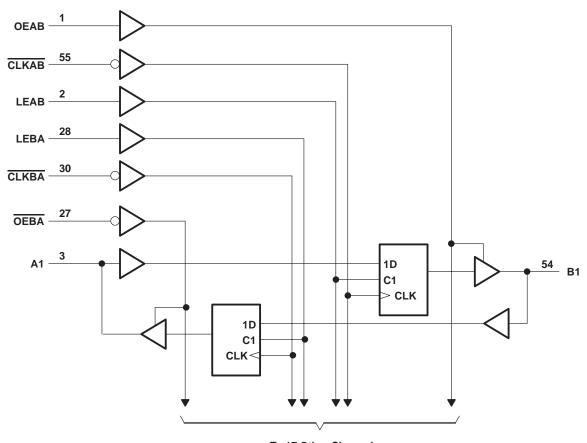
[§] Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	-0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16500B	96 mA
SN74ABT16500B	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



recommended operating conditions (see Note 3)

			SN54ABT	16500B	SN74ABT1	6500B	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	2	2		V
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0 4	Vcc	0	Vcc	V
IOH	High-level output current		1	-24		-32	mA
loL	Low-level output current		2	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	30%	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature			125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

SN54ABT16500B, SN74ABT16500B 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CO.	NDITIONS	Т	A = 25°C	;	SN54ABT	16500B	SN74ABT1	16500B	UNIT	
PAP	KAMETER	1231 CO	NDITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
٧ıK		$V_{CC} = 4.5 \text{ V}, \qquad I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	I _{OH} = -3 mA	2.5			2.5		2.5			
V		V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3		V	
VOH		V 45V	I _{OH} = -24 mA	2			2				V	
		V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2			
V/01		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _C C = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
1.	Control inputs	$V_{CC} = 0$ to 5.5 V, $V_I = V_{CC}$ or GND $V_{CC} = 2.1$ V to 5.5 V, $V_I = V_{CC}$ or GND				±1		±1		±1	μΑ	
ΙΙ	A or B ports					±20	,4	±20		±20	μΑ	
lo [‡]	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.5 \text{ V}$		V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
lozpu	_J §	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}$	/, OE or OE = X			±50	ROD	±50		±50	μА	
lozpd)§	V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 \	/, OE or OE = X			±50		±50		±50	μА	
IOZH		$\frac{V_{CC}}{OE} = 2.1 \text{ V to } 5.5$ $OE \ge 2 \text{ V, } OE \le 0.8$	V, V _O = 2.7 V, s V [#]			10		10		10	μΑ	
lozL¶		$\frac{\text{V}_{\text{C}}\text{C}}{\text{OE}} = 2.1 \text{ V to } 5.5$ $\frac{\text{OE}}{\text{OE}} \ge 2 \text{ V, OE} \le 0.8$	V, V _O = 0.5 V, 3 V [#]			-10		-10		-10	μА	
		V _{CC} = 5.5 V,	Outputs high			3		3		3		
ICC	A or B ports	$I_{O} = 0$,	Outputs low			36		36		36	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			3		3		3		
ΔICC		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				50		50		50	μΑ	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
C _{io}	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$	/		9						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This parameter is characterized, but not production tested.

The parameters I_{OZH} and I_{OZL} include the input leakage current.

[#] For V_{CC} between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

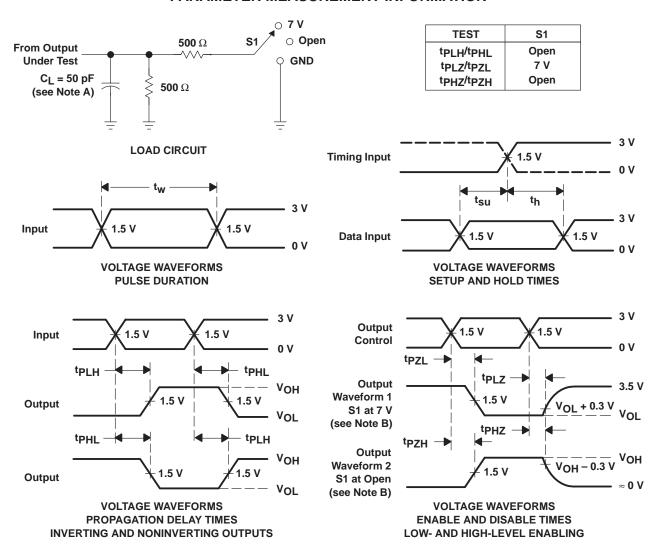
				SN54ABT	16500B	SN74ABT1	6500B	UNIT
				MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency			0	150	0	150	MHz
. +	Dulas duration	LEAB or LEBA high		2.5	2	2.5		
t _w †	Pulse duration	CLKAB or CLKBA high or low	3	Z	3		ns	
		A before CLKAB↓	3 4	92	3			
١.	Catua tima	B before CLKBA↓		3	,	3		
t _{su}	Setup time	A before LEAB↓ or B before LEBA↓ CLK high CLK low		3		1		ns
				2.5		2.5		
4.	Hold time	A after CLKAB↓ or B after CLKBA↓		0		0		20
th	Hold tille	A after LEAB↓ or B after LEBA↓	2		2		ns	

[†]This parameter is characterized, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(CC = 5 \ \ = 25°C	', ;	SN54ABT1	6500B	SN74ABT	16500B	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
fmax			150	200		150		150		MHz
t _{PLH}	A or B	B or A	1	2.5	3.6	1	4.2	1	4	ns
t _{PHL}	AUIB	BULA	1	3.2	4.5	1	5.1	1	4.9	115
t _{PLH}	1 E A D 1 E D A	B or A	1 3.2 4.5 1 5				5.6	1	5	ns
^t PHL	LEAB or LEBA	BULA	1	3.4	4.5	1 0	5.4	1	5	115
^t PLH	CLKAB or CLKBA	B or A	1	3.5	4.7	1	5.4	1	5.3	ns
t _{PHL}	CLKAB OF CLKBA	BOIA	1	3.5	4.7	2	5.4	1	5.3	115
^t PZH	OEAB or OEBA	B or A	1	3.4	4.6	O 1	5.3	1	5.1	ns
t _{PZL}	OEAB or OEBA	B or A	1.5	3.8	4.7	1.5	5.6	1.5	5.4	115
^t PHZ	OEAB or OEBA	B or A	1.5	4.5	5.7	1.5	6.9	1.5	6.5	20
t _{PLZ}	OEAD OF OEBA	D UI A	1.4	3.4	4.7	1.4	5.8	1.4	5.4	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16500BDGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16500BDLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16500BDGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16500BDLR	SSOP	DL	56	1000	346.0	346.0	49.0

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